

Intel Unveils New Multi-Level Cell Flash Products For Embedded Market Segment

Intel Corporation today introduced Intel StrataFlash Embedded Memory, a family of low-cost, high-performance NOR flash memory products targeted for embedded applications in such market segments as consumer electronics, industrial and wired communications. Intel's fourth-generation, Multi-Level Cell products target OEMs in embedded market segments that are increasingly requiring higher performance and density for flash memory. This type of performance is especially suited for platform designs ranging from digital cameras and household electronics to network routers and switches and handheld devices.

"Intel's proven, fourth-generation Multi-Level Cell technology delivers price-to-performance advantages for our embedded customers," said Darin Billerbeck, vice president and general manager, Intel Flash Products Group. "Intel StrataFlash Embedded Memory is our lowest cost-per-bit solution and offers developers of embedded applications a feature set that includes high performance, additional security options and low voltage for battery-backed applications."

Developed by Intel in 1988, NOR (Not-Or) flash is a rewritable memory chip that holds its content without power, making it ideal for embedded and cellular applications and other mobile devices. Intel's fourth-generation Multi-Level Cell technology delivers two bits of information in each memory cell, enabling smaller die sizes and higher densities.

Smart Choice for Embedded Applications

The new Intel StrataFlash Embedded Memory product family will offer a wide range of densities, from 64Mb to 1Gb, to provide an easy upgrade path for developers and eliminate redesign efforts while minimizing cost.

"We have successfully designed Intel StrataFlash Memory into our new, next-generation Spartan3E™ Reference Design Starter kit," said Sandeep Vij, vice president of worldwide marketing at Xilinx. "Now, with the performance and feature enhancements in its new embedded memory product family, Intel's solution will deliver increased value for us."

With the new product family, embedded system designers can choose from three package options to best meet their form factor needs, all of which are available in lead (Pb) and lead-free (Pb-free) packages. In addition, developers will benefit from fast access times for superior application performance - 85 nanosecond initial access times and subsequent 20 nanosecond bus speeds - along with multiple protection options for maximum security and low voltage for longer battery life.

Intel StrataFlash Embedded Memory in densities of 64Mb - 512Mb will be available in the second quarter of 2005 and can be coupled with royalty-free Intel flash memory software for improved data and file management. The 1Gb density device will be available in the second half of 2005.

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